

VACUUM EVACUATION MECHANISM

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Inventor(s): TOMINAGA SHINICHI
Applicant(s): SONY CORP
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Abstract

PURPOSE: To eliminate the adverse effect of reaction products on the piping or vacuum pump by heating the piping for evacuation system except a specific part and providing a temperature difference at the specific part of the piping so that the reaction products adhere collectively.

CONSTITUTION: A semiconductor machining unit 10 comprises a turbo vacuum pump 12, pipings 14, 15 for exhaust gas system, and a rotary vacuum pump 16. Each of heaters 18, 19 surrounding the piping comprises a rubber heater with nichrome wire, a mantle heater, or the like. With such structure, a temperature difference appears between a specific piping part 20 and the pipings 14, 15 in its front and rear and reaction products 24 are condensed on the inner wall 30 at the specific piping part 20. Since the exhaust system is protected against deterioration through a simple arrangement, labor and cost required for maintenance or replacement of parts can be reduced.

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